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Chenggen Quan
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Fook Siong Chau
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Introduction

The International Conference on Experimental Mechanics (ICEM 2014), in conjunction with 13th Asian Conference on Experimental Mechanics (ACEM13), was successfully held 15–17 November 2014, at Holiday Inn Atrium Hotel, Singapore. The conference was attended by 155 delegates from 14 countries.

The conference program included three keynote talks given by eminent experts in their respective fields. Professor Janice M. Dulieu-Barton of Southampton University (United Kingdom) delivered a lecture entitled "Imaging Techniques for Performance Assessments of Composite Structures based on Combining Thermoelastic Stress Analysis and Digital Image Correlation." Professor Qifeng Yu of National University of Defense Technology (China) presented the second keynote lecture, "Displacement-relay Videometric Methods for Surface Multi-position Subsidence Surveillance." Professor Anil Kishen of the University of Toronto (Canada) presented the third keynote lecture on "A Biomechanical Understanding of Dentin Hard Tissue."

Apart from the above, 101 papers were presented in 22 oral sessions and 28 papers were presented in 8 poster sessions. The conference covered topics ranging from traditional solid mechanics to fluid mechanics and dynamics, to the more current micro- and nano-mechanics, biomechanics, and smart structures and nondestructive testing (NDT). There were 8 special sessions: 1) Advances in 3D Profile and Shape Measurement; 2) Speckle and Speckle Shearing for NDT and Strain Measurement; 3) Dynamic Behavior of Materials and Structures, Vibration Analysis; 4) 3D Coordinate Measuring and Digital Image Correlation (DIC); 5) Microelectromechanical Systems (MEMS) and Application; 6) Composites for Marine and Offshore Applications; 7) Biomechanics; and 8) Digital Photoelasticity.

We take this opportunity to thank all speakers and authors for contributing to the success of the conference, members of the International Advisory Committee for their assistance and enthusiastic support, the session chairs, our sponsors, and the organizing committee for ensuring the efficient execution of the conference program.

Chenggen Quan
Chair, Scientific Program Committee, ICEM2014

Group photo of delegates at the opening ceremony